

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"6030891".pn.	US-PGPUB	OR	ON	2009/02/21 18:22
L2	1	"6030891".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:22
L4	1	2 and dielectric\$3	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:23
L6	1	2 and low same dielectric\$3	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:24
L7	1	"20050045206".pn.	US-PGPUB	OR	ON	2009/02/21 18:25
L8	1	7 and low-k	US-PGPUB	OR	ON	2009/02/21 18:25
L9	0	7 and sog	US-PGPUB	OR	ON	2009/02/21 18:29
L10	0	7 and hsq	US-PGPUB	OR	ON	2009/02/21 18:30
L11	1	2 and (pattern\$3 mask\$3) same (trench\$2 via\$1)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:33
L12	1	2 and solvent	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:39
L13	1	2 and bak\$3	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:43
L14	1	2 and metal	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:44
L15	1	2 and metal same deposit\$4	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:45

L18	1	2 and solvent\$1	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:49
L19	1	7 and component\$1	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:55
L20	0	7 and (water moisture)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 18:58
L21	1	2 and (water moiture)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 19:00
L22	1	2 and (organosilicate\$1 osg methylsilsesquioxane msq fluorine\$1 fluorine-dop\$3 fsg silicon\$1 silicon- dioxide\$2 "sio.sub.2")	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 19:32
L25	0	2 and (ash\$3 dry)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 19:36
L26	1	2 and (copper cuprous)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 19:41
L27	1	2 and (barrier seed)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 20:00
L28	0	2 and (acetamide DMAC)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 20:12
L29	0	2 and acid\$2	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 20:12
L30	1	7 and plasma	US-PGPUB	OR	ON	2009/02/21 20:23
L31	1	2 and (plasma rf photoresist ash\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 20:27
L32	0	2 and "250"	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/21 21:36
S1	1	"20050045206".pn.	US-PGPUB	OR	ON	2008/08/15 10:39
S2	6	("5643407" "20030104320" "20030008518" "6107202" "6417108" "20020058397").pn.	US-PGPUB; USPAT	OR	ON	2008/08/15 10:41

S3	1	S1 and anneal	US-PGPUB	OR	ON	2008/08/15 11:14
S4	1	S1 and minutes	US-PGPUB	OR	ON	2008/08/15 11:39
S5	1	"5643407".pn.	USPAT	OR	ON	2008/08/15 11:41
S6	1	S5 and (minute\$1 seconds)	USPAT	OR	ON	2008/08/15 11:42
S7	1	S1 and solvent	US-PGPUB	OR	ON	2008/08/15 12:17
S8	0	S1 and (moistur\$5 water aqueous)	US-PGPUB	OR	ON	2008/08/15 12:19
S9	1	S1 and component\$1	US-PGPUB	OR	ON	2008/08/15 12:19
S10	0	S1 and (moistur\$5 water aqueous vapor\$7)	US-PGPUB	OR	ON	2008/08/15 12:23
S11	1	S5 and (moistur\$5 water aqueous vapor\$7)	USPAT	OR	ON	2008/08/15 12:23
S12	1	"20050045206".pn.	US-PGPUB	OR	ON	2008/08/21 15:57
S13	1	S12 and clean\$4	US-PGPUB	OR	ON	2008/08/21 15:57
S14	6	("5643407" "20030104320" "20030008518" "6107202" "6417108" "20020058397").pn.	US-PGPUB; USPAT	OR	ON	2008/08/21 15:58
S15	4	S14 and clean\$4	US-PGPUB; USPAT	OR	ON	2008/08/21 15:58
S16	0	S12 and embodi\$5	US-PGPUB	OR	ON	2008/08/21 16:52

S17	11	("20020058397"   "20030008518"   "20030104320"   "20030194877"   "20040060579"   "5643407"   "5798323"   "6100183"   "6107202"   "6417108"   "6713402").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 10:55
S18	2194	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluori\$3 "silicate glass" sio2 (silicon same dioxide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 11:08
S19	0	(pattern patterning) and (trench via) and "low-k" and (solvent acid (dimethyl same acetamide) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate msq methylsilsesquioxane fsg fluorine fluoride "silicate glass" sio2 (silicon same dioxide))	USOCR	OR	ON	2008/08/25 11:09
S20	136	S18 and "134".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:10
S22	96	S20 and 134/1,1,2,2,3,19,26,16,21,34,35,37.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:15
S23	79	S22 and photoresist\$1	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:16
S24	79	S23 and plasma	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:16
S25	36	S24 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:17
S26	0	S22 and S17	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:18

S27	11	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 11:18
S28	47	S25 S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 11:18
S29	0	S28 and S17	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:22
S30	1	"20050045206".pn.	US-PGPUB	OR	ON	2008/08/25 11:28
S31	1	S30 and boil\$3	US-PGPUB	OR	ON	2008/08/25 11:28
S32	3	S17 and low-k	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:42
S33	9	S17 and dielectric	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:44
S34	1	"5643407".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:47
S35	0	S34 and dielectric same low	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:47
S36	0	S34 and low-k	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:47
S37	0	S34 and capacit\$5	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:58
S38	1	"6100183".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 12:03

S39	1	S38 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 12:03
S40	47	S28 and low-k	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 12:16
S41	37	S40 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 12:17
S42	11	("20020058397"   "20030008518"   "20030104320"   "20030194877"   "20040060579"   "5643407"   "5798323"   "6100183"   "6107202"   "6417108"   "6713402").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:21
S43	2194	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluoris\$3 "silicate glass" sio2 (silicon same dioxide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 14:22
S44	136	S43 and "134".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
S45	96	S44 and 134/1,1,2,2,3,19,26,16,21,34,35,37.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
S46	79	S45 and photoresist\$1	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
S47	79	S46 and plasma	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
S48	36	S47 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22

S49	11	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:22
S50	47	S48 S49	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:22
S51	58	S42 S50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:24
S52	11	S51 and (wet near3 (clean\$4 strip\$4)) same (dry near3 (clean\$4 strip\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:25
S53	2	"6554912".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:34
S54	2	S53 and (h2 hydrogen o2 oxygen inert n2 nitrogen)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:35

S55	1	S53 and plasma same (h2 hydrogen o2 oxygen inert n2 nitrogen)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:36
S56	2	"5643407".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:49
S57	4	S53 S56	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:49
S58	2	S57 and (copper cu)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:49
S59	3	S57 and deposit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:52
S60	27	S51 and (copper cu cuprous) same deposit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 16:07



S61	11	S60 and (copper cu cuprous) near3 deposit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 16:08
S62	2	S57 and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluori\$3 "silicate glass" sio2 (silicon same dioxide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 16:29
S63	1	S57 and (dmac (dimethyl same acetamide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 16:57
S64	1	S57 and acid\$2	US-PGPUB; USPAT	OR	ON	2008/08/25 17:00
S65	1	S57 and (critical dimension\$1 extru\$5)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:21
S66	36	S47 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 17:22
S67	1	S47 and ((critial same dimension\$1) extru\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 17:23
S68	1	S67 and ((critial same dimension\$1) extru\$5) same (anneal\$4 bak\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 17:26
S69	69	wafer\$1 and ((critical same dimension\$1) (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:27
S70	820	wafer\$1 and ((critical same dimension\$1) (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28
S71	322	S70 and wafer\$1 same ((critical same dimension \$1) (metal\$3 same extru\$5)) same (anneal\$4 bak \$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28
S72	1	S71 and wafer\$1 same ((critical same dimension \$1) and (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28

S73	1	S71 and wafer\$1 and ((critical same dimension\$1) and (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28
S74	8	((critical same dimension\$1) and (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:29
S75	2	"6417108".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 17:42
S76	0	S75 and (dmac (dimethyl same acetamide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 17:47
S77	12	("20020058397"   "20030008518"   "20030104320"   "20030194877"   "20040060579"   "5643407"   "5798323"   "6100183"   "6107202"   "6417108"   "6554912"   "6713402").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:40
S78	1	"20050045206".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:43
S79	2	("2005/0045206").URPN.	USPAT	OR	ON	2009/02/20 14:44
S80	15	("5705435"   "5723383"   "5741626"   "5773201"   "5877075"   "6251771"   "6277733"   "6323121"   "6342446").PN. OR ("6713402").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:46
S81	16	("20020013239"   "3979241"   "4230523"   "5320709"   "5571447"   "5792274"   "5905063"   "5972862"   "6068000"   "6350560"   "6475966").PN. OR ("6554912").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:46
S82	14	("5152857"   "5340435"   "5371037"   "5374564"   "5668045"   "5937312"   "5952694"   "6090688"   "6110391").PN. OR ("6417108").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:46

S83	16	("3988256"   "4067100"   "4165294"   "4567132"   "4786578"   "4824762"   "5201960"   "5362608"   "5688618"   "5904156"   "6000411"   "6002202"). PN. OR ("6107202").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:46
S84	9	("5932487").PN. OR ("6100183").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:46
S85	52	("4395348"   "4617251"   "4732695"   "4770713"   "4824763"   "4904571"   "5174816"   "5279771"   "5308745"   "5334332"   "5417877"   "5472830"   "5496491"   "5507978"   "5545353"   "5563119"   "5567574"   "5571447"   "5597678"   "5648324"   "5665688"   "5709737").PN. OR ("5798323"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:46
S86	31	("5003062"   "5219792"   "5266525"   "5320983"   "5334332"   "5393702").PN. OR ("5643407"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:47
S87	11	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluorio\$3 "silicate glass" sio2 (silicon same dioxide\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2009/02/20 14:49
S88	86	(S77 S80 S81 S82 S83 S84 S85 S86 S87) and (anneal\$4 bak\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2009/02/20 14:50
S89	84	S88 and (minute\$ seconds)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2009/02/20 14:50
S90	1	S89	FPRS; EPO; JPO; DERWENT	OR	ON	2009/02/20 14:51

S91	1	S78 and (furnace hot-plate plate)	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 14:55
S92	1	"6603204".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 15:00
S93	1	"20020117760".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 15:00
S94	1	S93 and seconds	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 15:01
S95	84	S88 and (minute\$1 seconds)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2009/02/20 15:23
S96	1	S95 and (minute\$1 seconds)	FPRS; EPO; JPO; DERWENT	OR	ON	2009/02/20 15:23
S97	61	S88 and (minute\$ seconds) same (bak\$3 anneal \$4)	US-PGPUB; USPAT	OR	ON	2009/02/20 15:32
S98	1	"6030891".pn.	US-PGPUB; USPAT	OR	ON	2009/02/20 15:43
S99	1	S98 and (hot-plate hotplate plate furnace asher)	US-PGPUB; USPAT	OR	ON	2009/02/20 15:44
S100	1	S98 and plasma	US-PGPUB; USPAT	OR	ON	2009/02/20 15:48
S101	1	S98 and ((anneal\$4 bak\$4) plasma)	US-PGPUB; USPAT	OR	ON	2009/02/20 15:50
S102	1	"5952694".pn. and plasma	US-PGPUB; USPAT	OR	ON	2009/02/20 15:57
S103	1	"5003062".pn. and plasma	US-PGPUB; USPAT	OR	ON	2009/02/20 16:08
S104	0	"4617251".pn. and plasma	US-PGPUB; USPAT	OR	ON	2009/02/20 16:11

S105	1	S78 and celsius	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 16:12
S106	0	S88	USOCR	OR	ON	2009/02/20 16:16
S107	1	S78 and temperature	US-PGPUB; USPAT; USOCR	OR	ON	2009/02/20 16:20
S108	2	S98 S103	US-PGPUB; USPAT	OR	ON	2009/02/20 16:21
S109	1	S108 and (furnace ash\$3)	US-PGPUB; USPAT	OR	ON	2009/02/20 16:22
S110	2	S108 and plasma	US-PGPUB; USPAT	OR	ON	2009/02/20 16:22
S111	2	S108 and (vacuum pressure torr atmosphere\$1 atm pa kpa)	US-PGPUB; USPAT	OR	ON	2009/02/20 16:25
S112	2	S108 and (vacuum pressure torr atmosphere\$1 atm pa kpa anneal\$4 bak\$4 plasma)	US-PGPUB; USPAT	OR	ON	2009/02/20 16:27
S113	2	S108 and (plate hotplate hot-plate furnace ash\$3)	US-PGPUB; USPAT	OR	ON	2009/02/20 16:38
S114	1	S108 and wet same solvent\$1	US-PGPUB; USPAT	OR	ON	2009/02/20 16:42

2/ 21/ 2009 10:01:29 PM

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